## **EAST Search History**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	(("6305067") or ("6570085")).PN.	US-PGPUB; USPAT	OR	OFF	2007/03/22 11:57
S2	112	"204".clas. and substrate and plating and (nickel or Ni) and (copper or Cu) and steel and target and sputter	US-PGPUB; USPAT	ADJ <sub>.</sub>	ON	2007/03/21 17:18
S3	2002	"204".clas. and target and sputtering adj apparatus	US-PGPUB; USPAT	ADJ	ON	2007/03/22 10:55
S4	350	"204".clas. and target and sputtering adj apparatus and substrate and (plating or layering)	US-PGPUB; USPAT	ADJ	ON	2007/03/22 10:56
S5	170	"204".clas. and target and sputtering adj apparatus and substrate and (plating or layering)and vacuum adj chamber	US-PGPUB; USPAT	ADJ	ON	2007/03/22 10:56
S6	142	"204".clas. and target and sputtering adj apparatus and substrate and (plating or layering)and vacuum adj chamber and argon	US-PGPUB; USPAT	ADJ	ON	2007/03/22 12:03
S7	0	"204".clas. and target and sputtering adj apparatus and substrate and (plating or layering)and vacuum adj chamber and argon and (electically conductive layer)	US-PGPUB; USPAT	ADJ	ON	2007/03/22 10:58
S8	4	"204".clas. and target and sputtering adj apparatus and substrate and (plating or layering)and vacuum adj chamber and argon and (electrically conductive layer)	US-PGPUB; USPAT	ADJ	ON	2007/03/22 10:58
S9	2887	kulkarni	US-PGPUB; USPAT	ADJ	ON-	2007/03/22 11:50
S10	1	("6283357").PN.	US-PGPUB; USPAT	OR	OFF	2007/03/22 11:50
S11	1	("5593551").PN.	US-PGPUB; USPAT	OR	OFF	2007/03/22 11:57
S12	. 105	"204".clas. and target and sputtering adj apparatus and substrate and vacuum adj chamber and ((direct current) or DC) and (power density)	US-PGPUB; USPAT	ADJ 	ON	2007/03/22 12:33

## **EAST Search History**

S13	103	"204".clas. and target and sputtering adj apparatus and substrate and vacuum adj chamber and resin	US-PGPUB; USPAT	ADJ	ON	2007/03/22 14:05
S14	12	"204".clas. and target and sputtering adj apparatus and substrate and vacuum adj chamber and ((direct current) or DC) and (power density) and resin	US-PGPUB; USPAT	ADJ	ON	2007/03/22 18:03
S15	0	"204".clas. and target and sputtering adj apparatus and substrate and resin and polystryene	US-PGPUB; USPAT	ADJ	ON	2007/03/22 13:39
Š16	31	"204".clas. and target and sputtering adj apparatus and substrate and resin and polystyrene	US-PGPUB; USPAT	ADJ	ON	2007/03/22 13:39
S17	22	"204".clas. and composite target and sputtering adj apparatus and substrate and vacuum adj chamber	US-PGPUB; USPAT	ADJ	ON	2007/03/22 14:05
S18	516	"204".clas. and target and sputtering adj apparatus and substrate and vacuum adj chamber and ((direct current) or DC) and (voltage or volt)	US-PGPUB; USPAT	ADJ	ON	2007/03/22 18:03
S19	95	"204".clas. and target and sputtering adj apparatus and substrate and vacuum adj chamber and ((direct current) or DC) and (voltage or volt) and (power density)	US-PGPUB; USPAT	ADJ	ON	2007/03/22 18:05